



- 1 Substrate: 3.18mm $\pm 0.25\text{mm}$ [0.125" $\pm 0.001\text{"}$] FR4/G10 or equivalent high temp material. 17 μm [1/2 oz.] Cu clad. SnPb plating.
- 2 Solder ball: Eutectic Sn63Pb37

Description: BGA Surface Mount Adaptor
 Surface mount land pattern to solder balls. To be used with GHz sockets.

Tolerances: diameters $\pm 0.03\text{mm}$ [$\pm 0.001\text{"}$], PCB perimeters $\pm 0.13\text{mm}$ [$\pm 0.005\text{"}$], PCB thicknesses $\pm 0.18\text{mm}$ [$\pm 0.007\text{"}$], pitches (from true position) $\pm 0.08\text{mm}$ [$\pm 0.003\text{"}$], all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005\text{"}$] unless stated otherwise. Materials and specifications are subject to change without notice.

	SF-BGA456D-B-05 Drawing © 2002 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Status: Released	Scale: 2:1	Rev: B
		Drawing: H. Hansen File: SF-BGA456D-B-05 Dwg		Date: 8/14/02 Modified: 6/16/05